#9/660,324-Conf. #2581   September 12, 2000   F. Toledo   2 #picant(s): Kie Y. Ahn, et al.  Invention: SILICON MULTI-CHIP MODULE PACKAGING WITH INTEGRATED PASSIVE COMPONENTS AND METHOD OF MAKING  **TO THE COMMISSIONER FOR PATENTS**  Transmitted herewith is an amendment in the above-identified application.  The fee has been calculated and is transmitted as shown below.  **CLAIMS AS AMENDED**    Remaining After Previously Extra Claims Present Previously Paid   Previously Present Previously Paid   Previously Present   Rate	Invention:  SILICON MULTI-CHIP MODULE PACKAGING WITH INTEGRATED PASSIVE COMPONENTS AND METHOD OF MAKING  TO THE COMMISSIONER FOR PATENTS  Transmitted herewith is an amendment in the above-identified application.  The fee has been calculated and is transmitted as shown below.  CLAIMS AS AMENDED    Claims		- No		Filipa	Doto	Examiner	Art
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Claims  Multiple Dependent Claims (check if applicable)  Other fee (please specify):  TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:  X Large Entity  No additional fee is required for this amendment.  Please charge Deposit Account No. in the amount of,\$ A duplicate copy of this sheet is enclosed.  A check in the amount of \$	Claims  Multiple Dependent Claims (check if applicable)  Other fee (please specify):  TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:  X Large Entity  No additional fee is required for this amendment.  Please charge Deposit Account No. in the amount of,\$ A duplicate copy of this sheet is enclosed.  A check in the amount of \$		35	- 3	<u> </u>		х	0.0
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A duplicate copy of this sheet is enclosed.  A check in the amount of \$ to cover the filing fee is enclosed.  X The Commissioner is hereby authorized to charge and credit Deposit Account No	A duplicate copy of this sheet is enclosed.  A check in the amount of \$ to cover the filing fee is enclosed.  X The Commissioner is hereby authorized to charge and credit Deposit Account No			d for th	is ame	endment.	Small Entity	•
The Commissioner is hereby authorized to charge and credit Deposit Account No	The Commissioner is hereby authorized to charge and credit Deposit Account No			eet is e	nclose	d.	-	
as described below. A duplicate copy of this sheet is enclosed.    X   Credit any overpayment.     X   Charge any additional filing or application processing fees required under 37 CFR 1.16 and     X   Charge any additional filing or application processing fees required under 37 CFR 1.16 and     Stephen A. Soffen     April 23, 2002     Stephen A. Soffen     Attorney Reg. No.: 31,063     DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP     2101 L Street NW	as described below. A duplicate copy of this sheet is enclosed.    X   Credit any overpayment.     X   Charge any additional filing or application processing fees required under 37 CFR 1.16 and     Stephen A. Soffen     April 23, 2002     Stephen A. Soffen     Attorney Reg. No.: 31,063     DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP     2101 L Street NW	A check in the	he amount of \$			to cover	the filing fee is end	
Charge any additional filing or application processing fees required under 37 CFR 1.16 and  Dated: April 23, 2002  Stephen A. Soffen  Attorney Reg. No.: 31,063  DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP  2101 L Street NW	Charge any additional filing or application processing fees required under 37 CFR 1.16 and  Dated: April 23, 2002  Stephen A. Soffen  Attorney Reg. No.: 31,063  DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP  2101 L Street NW	V   TI - O						ount No04-1
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